

功能

- AT切割晶体结构
- 超微型密封陶瓷表面贴装
- 高温、高精度和可靠性特点
- 封装尺寸:5.0×3.2×0.8mm
- 符合RoHS, 无铅和无卤素标准。

应用

- 音频设备
- 便携式设备
- 短距离无线模块
- 计算机、调制解调器、微处理器



电气规格

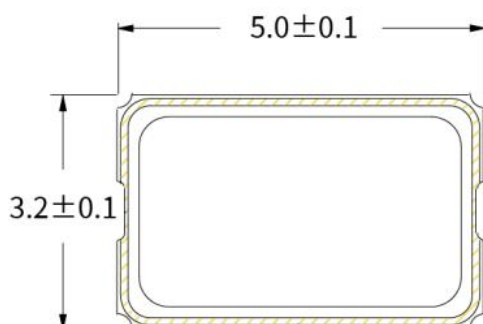
项目	标记符号	最小值	典型值	最大值	单位	备注
频率范围	FL	8.000		50	MHZ	
振荡模式		Fundamental(AT-cut)				
常温频差		-10	~	+10	PPM	25°±2°
温度频差	Topr	- 40	~	+85	℃	±20PPM
储存温度	Tstg	- 40	~	+125	℃	
静态电容	C0	~	~	3	PF	MAX
激励功率	DL	~	10	300	uW	
负载电容	CL	8	~	20	PF	可定制
绝缘电阻	IR	~	~	500	MΩ	
年老化率		-3	~	+3		每年

等效电阻

频率范围	等效电阻(Max.)
$8\text{MHz} \leq \text{Freq.} < 10\text{MHz}$	100 Ω
$10\text{MHz} \leq \text{Freq.} < 16\text{MHz}$	80 Ω
$16\text{MHz} \leq \text{Freq.} < 20\text{MHz}$	50 Ω
$20\text{MHz} \leq \text{Freq.} < 24\text{MHz}$	40 Ω
$24\text{MHz} \leq \text{Freq.} < 50\text{MHz}$	30 Ω

产品尺寸 (单位:mm)

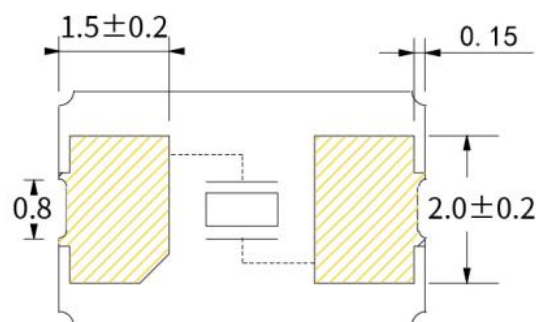
● TOP VIEW



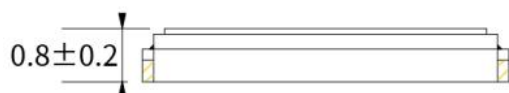
● SIDE VIEW



● BOTTOM VIEW

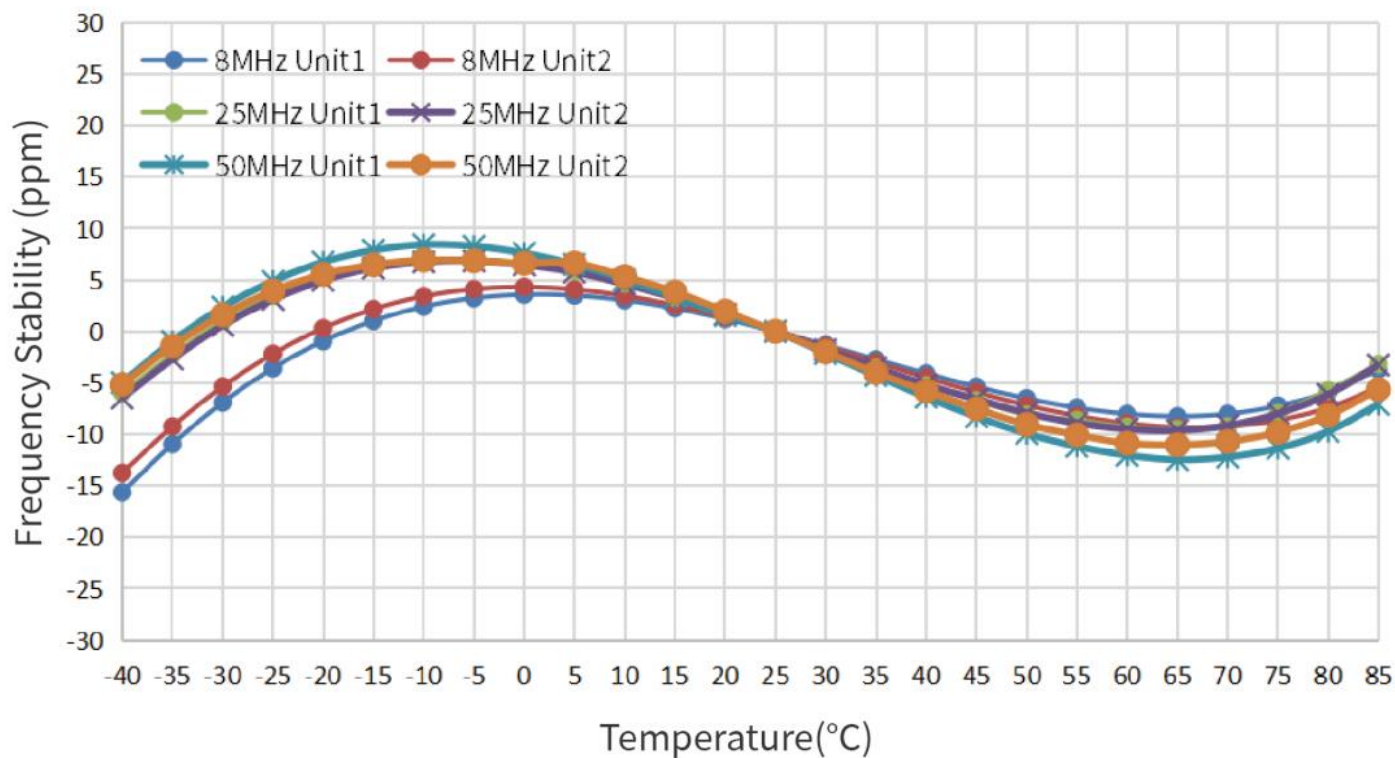


● SIDE VIEW



频率温度特性

频率稳定性与温度变化 (5032)

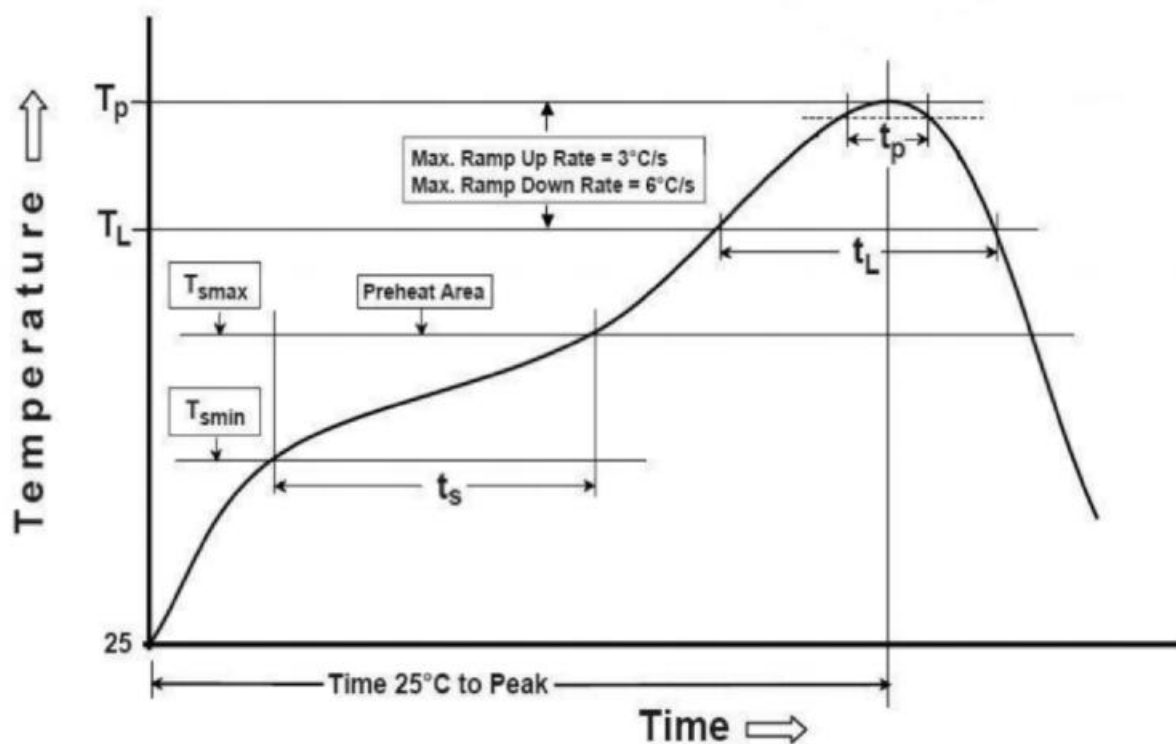
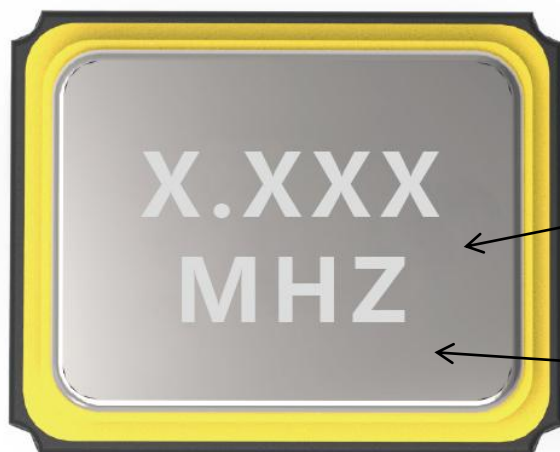


产品结构及印字

产品结构



印字

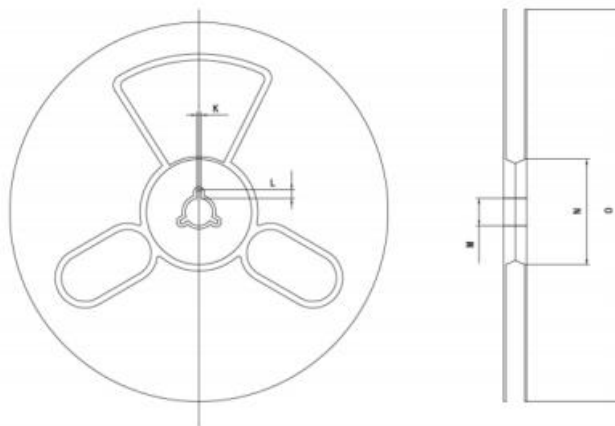


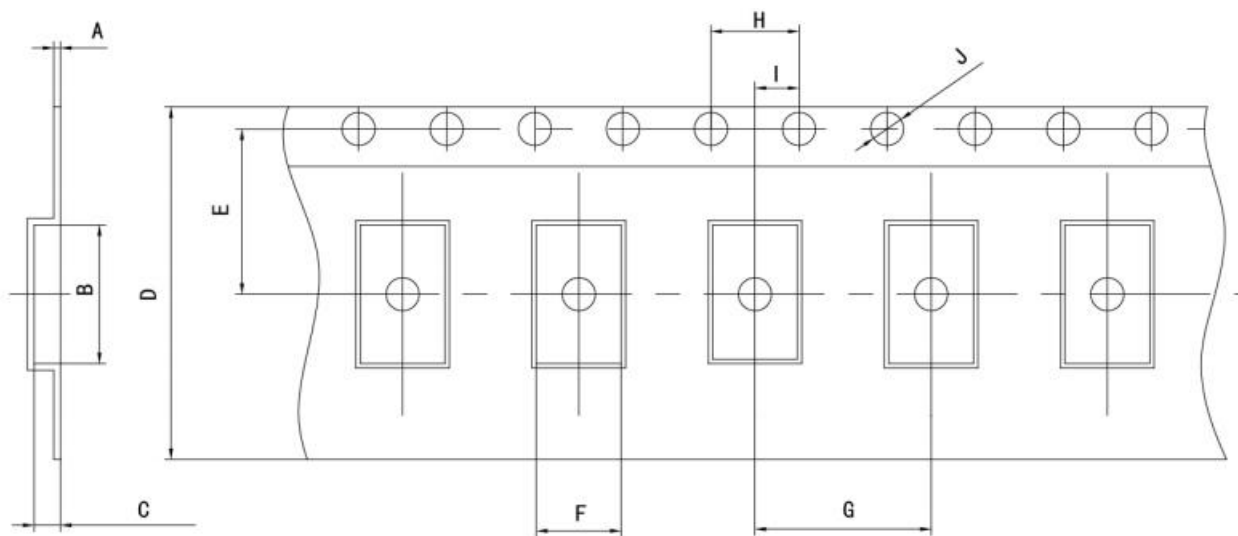
回流焊建议

Profile Feature	Sn - Pb Eutectic Assembly	Preheat / Soak
Preheat / Soak ● Temperature Min (Ts min) ● Temperature Max (Ts max) ● Time (Ts min to Ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-120 seconds
Ramp - up rate (TL to Tp)	3°C/ second max.	3°C/ second max.
Time maintained above ● Liquidous temperature (TL) ● Time (tL) maintained above TL	183°C 60-150 seconds	217°C 60-150 seconds
Peak package body temperature (Tp)	235°C	260°C
Time within 5° C of the specified classification temperature (Tp)	20 seconds	30 seconds
Ramp - down rate (Tp to TL)	6°C/ second max.	6°C/ second max.
Time 25° C to peak temperature	6 minutes max.	8 minutes max.
Suggest reflow times	2 Times max.	

包装信息

T=卷带（每卷1000/pcs）





卷带尺寸

A	B	C	D	E	F	G	H	I	J	K	L	M	N	O
0.3±0.05	5.4±0.1	1.2±0.1	12±0.3	5.5±0.1	3.6±0.1	8.0±0.1	4.0±0.1	2.0±0.1	φ1.5±0.1	2.0±0.2	4.0±1.0	φ13±0.5	φ60±1	φ180±1